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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: George Hsieh
Title: USING THE WAVE SOLDERING PROCESS TO ATTACH MOTHERBOARD CHIPSET HEAT SINKS
Docket No.: 884.462US1 Serial No.: 09/897,320
Filed: June 29, 2001 Due Date: N/A
Examiner: Unknown Group Art Unit: 2835

Commissioner for Patents
Washington, D.C. 20231

We are transmitting herewith the following attached items (as indicated with an "X"):

A return postcard.
 An Information Disclosure Statement (1pgs.), Form 1449 (1 pgs.), and copies of 2 cited references.

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By: Ann M. McCrackin
Atty: Ann M. McCrackin
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on this 14 day of February, 2002.

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(G)

P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

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